

MAX33074E Shield EV Kit

Evaluates: MAX33074E

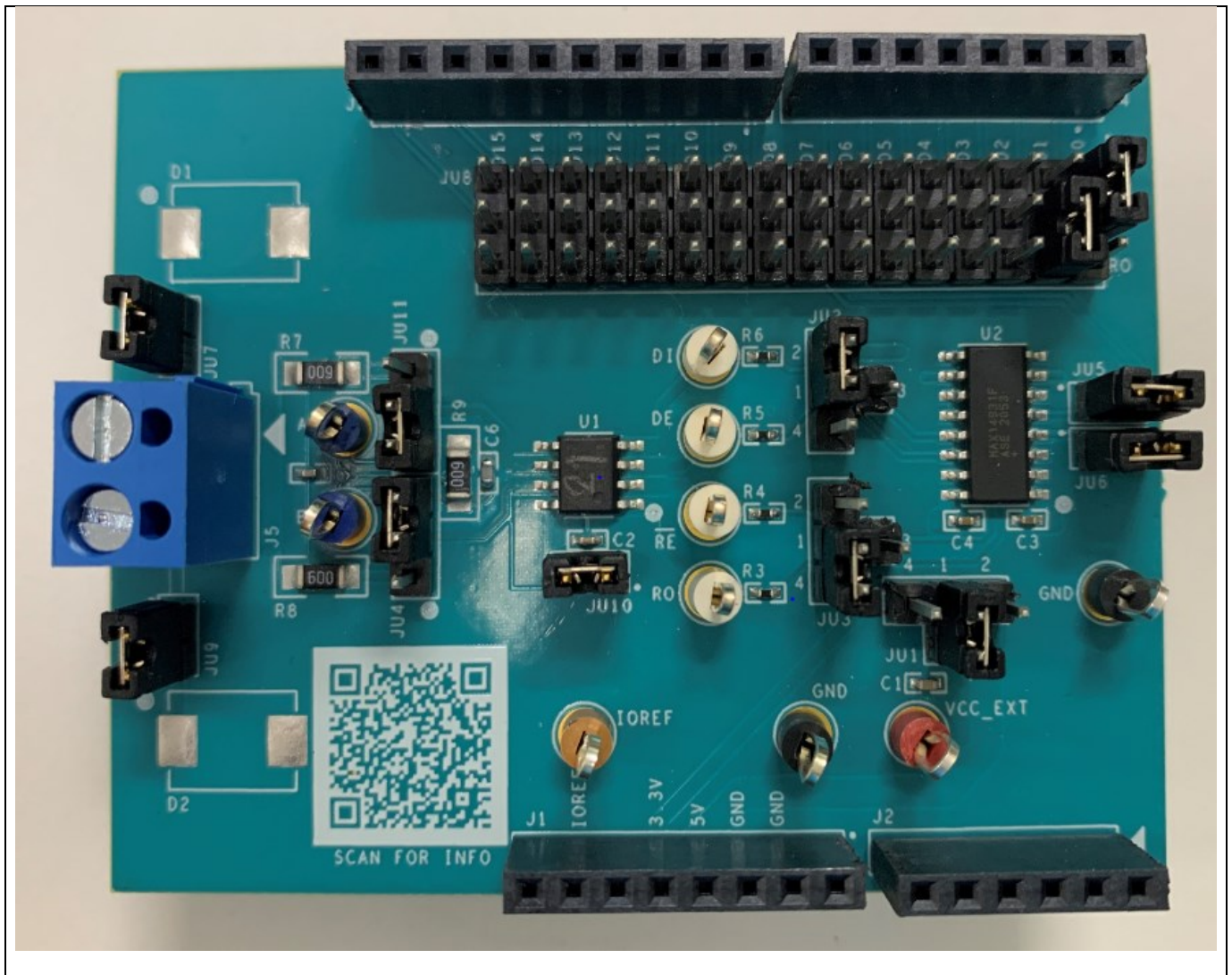
General Description

The MAX33074E Shield evaluation kit (EV kit) is a fully assembled and tested printed circuit board (PCB) that demonstrates the functionality of the MAX33074E, a half-duplex RS-485 transceiver with $\pm 65V$ fault protection, extended $\pm 40V$ common-mode range, and $\pm 40kV$ ESD Human Body Model (HBM) for A, B data lines. The EV kit features a digital isolator, which is used as a level translator between the RS-485 transceiver and the controller interface.

Features

- Easy Evaluation of the MAX33074E
- I/O Interface Compatibility from 1.71V to 5.5V
- Proven PCB Layout
- Compatible with Arm® Mbed™ Platform/Arduino®
- Fully Assembled and Tested

EV Kit Photo



Quick Start

Required Equipment

- MAX33074E Shield EV kit
- +5V, 500mA DC Power Supply
- Signal/function generator that can generate 10MHz square wave signal
- Oscilloscope

Procedure

The EV kit is fully assembled and tested. Follow these steps to verify board operation:

1. Place the MAX33074E shield EV kit on a nonconductive surface to ensure that nothing on the PCB gets shorted to the workspace.
2. Verify all the jumpers are in their default position as shown in [Table 1](#).
3. With +5V power supply disabled, connect the positive terminal to VCC_EXT and IOREF test points. Connect the negative terminal to the GND test point.
4. Connect the positive terminal of the function generator to D0 (pin 1 of J4) and the negative terminal to any of the GND test points on the shield EV kit.
5. Set the function generator to output a 10MHz square wave between 0V and 5V, and then enable function generator output.
6. Turn on the +5V DC power supply.
7. Connect an oscilloscope probe on D1 (pin 2 of J4) and verify that the D1 output signal (RO) matches the D0 input signal (DI).

Table 1. Jumper Settings

JUMPER	SHUNT POSITION	DESCRIPTION
JU1	1-2	VCC is shorted to +5V supply from shield header
	1-3*	VCC is shorted to VCC_EXT external supply
	1-4	VCC is shorted to +3.3V supply from shield header
	Open	VCC is open
JU2	1-2*	DE is shorted to VCC
	1-3	DE is connected to level shifter output
	1-4	DE is shorted to GND
	Open	DE is open
JU3	1-2	RE is shorted to VCC
	1-3	RE is connected to level shifter output
	1-4*	RE is shorted to GND
	Open	RE is open
JU4 and JU11	1-2	Connects 120Ω between A and B
	2-3*	Connects 60Ω between A and B
	Open	No load is connected between A and B
JU5	1-2*	Connects RE to D7 of J4
	Open	Disconnects RE from D7 of J4
JU6	1-2*	Connects DE to D6 of J4
	Open	Disconnects DE from D6 of J4
JU7	1-2*	TVS Diode (DNI) connected to A
	Open	TVS Diode (DNI) disconnected from A
JU8	—	See Table 2
JU9	1-2*	TVS Diode (DNI) connected to B
	Open	TVS Diode (DNI) disconnected from B
JU10	1-2*	Connects VCC pin of U1 to supply rail
	Open	Disconnects VCC pin of U1 from supply rail

*Default jumper state.

Detailed Description of Hardware

The MAX33074E Shield EV kit is a fully assembled and tested circuit board for evaluating the MAX33074E, a fault-protected half-duplex RS-485 transceiver (U1) with $\pm 65V$ of fault protection. The shield EV kit is designed to evaluate MAX33074E alone or in a RS-485 system. The shield enables the Arduino or Mbed platform to communicate on a RS-485 bus. The MAX14931 digital isolator is used as a level translator with a 1.71V to 5.5V supply range. Remove the 0Ω resistor R6 to apply the transmitter input signal directly on the DI test point. Likewise, remove the 0Ω resistor R3 to measure the receiver output signal directly on the RO test point.

If external protection is desired beyond the device's built-in protection, the shield also features footprints for TVS diodes (D1 and D2) that can be connected to the A and B lines using JU7 and JU9, respectively.

Powering the Board

This shield EV kit requires two power supplies: one 3V to 5.5V supply for the MAX33074E (U1) transceiver applied at the VCC_EXT test point, and one 1.71V to 5.5V supply for the microcontroller domain applied at the IOREF test point. When the shield EV kit is used with an Arduino/Mbed platform, the power supply for U1 can also come from the Arduino/Mbed platform's 3.3V or 5V rail. Place the shunt on 2-3 position of JU1 to connect VCC to VCC_EXT pin. Place the shunt of JU1 on 1-2 position or 1-4 position to connect the VCC of U1 to the Arduino/Mbed platform 3.3V or 5V supply rail, respectively. In this scenario, IOREF is directly taken from the Arduino/Mbed platform header.

Onboard Termination

A properly terminated RS-485 bus is terminated at each end with the characteristic impedance of the cable. For CAT5 or CAT6 cables, this is typically 120Ω on each end for a 60Ω load on the RS-485 driver. This shield EV kit features a selectable 60Ω or 120Ω load circuit between the A and B driver outputs. If the board is evaluated in a system and is connected at the end of the cable, then select the 120Ω termination. The termination resistors on the shield should be changed to 60Ω with a $100pF$ load to simulate a complete system load during evaluation.

DI and RO Configuration

Digital Channels of DI and RO are selected through JU8. It consists of three columns and 16 rows. The columns labeled DI and RO are connected to MAX33074E through digital isolator (MAX14931FASE+ (U2)). The middle column contains the digital I/O pins (D0 to D15) from the Arduino/Mbed platform header. This provides flexibility for the user to select different resources from the microcontroller to transmit and receive signals to and from the RS-485 transceiver. [Table 2](#) shows the list of JU8 jumper options.

Table 2. DI and RO Jumper Settings

JUMPER	SHUNT POSITION	DESCRIPTION
JU8	1-2*	Connects DI to D0
	4-5	Connects DI to D1
	7-8	Connects DI to D2
	10-11	Connects DI to D3
	13-14	Connects DI to D4
	16-17	Connects DI to D5
	19-20	Connects DI to D6
	22-23	Connects DI to D7
	25-26	Connects DI to D8
	28-29	Connects DI to D9
	31-32	Connects DI to D10
	34-35	Connects DI to D11
	37-38	Connects DI to D12
	40-41	Connects DI to D13
	43-44	Connects DI to D14
	46-47	Connects DI to D15
	2-3	Connects RO to D0
	5-6*	Connects RO to D1
	8-9	Connects RO to D2
	11-12	Connects RO to D3
	14-15	Connects RO to D4
	17-18	Connects RO to D5
	20-21	Connects RO to D6
	23-24	Connects RO to D7
	26-27	Connects RO to D8
	29-30	Connects RO to D9
	32-33	Connects RO to D10
	35-36	Connects RO to D11
	38-39	Connects RO to D12
	41-42	Connects RO to D13
44-45	Connects RO to D14	
47-48	Connects RO to D15	

*Default jumper state.

Flexible Interface Options

The shield EV kit allows multiple points of connection to the MAX33074E transceiver. This shield board could be placed on an Arduino/Mbed platform compatible board to connect all the digital pins (DI, DE, RO, RE) through the J3, J4 headers. These signals could also be connected directly at their respective test points on the board, bypassing the digital isolator (U2). The A, B signals are connected to a terminal block (J5) to easily connect to a twisted pair cable. Alternately, the A, B test points can be used.

PCB Layout for Thermal Dissipation

PCB layout can affect the performance of the transceiver in conditions with high common-mode voltage at high ambient temperature. The layout of the shield EV kit is designed to maximize thermal performance in such cases. Larger copper pads are used for all the pins. The GND pad is connected to exposed pad with vias to bottom side of the shield. A thick trace from the VCC pad to JU10 allows for greater heat dissipation at the VCC pin.

Ordering Information

PART	TYPE
MAX33074ESHLD#	EV Kit

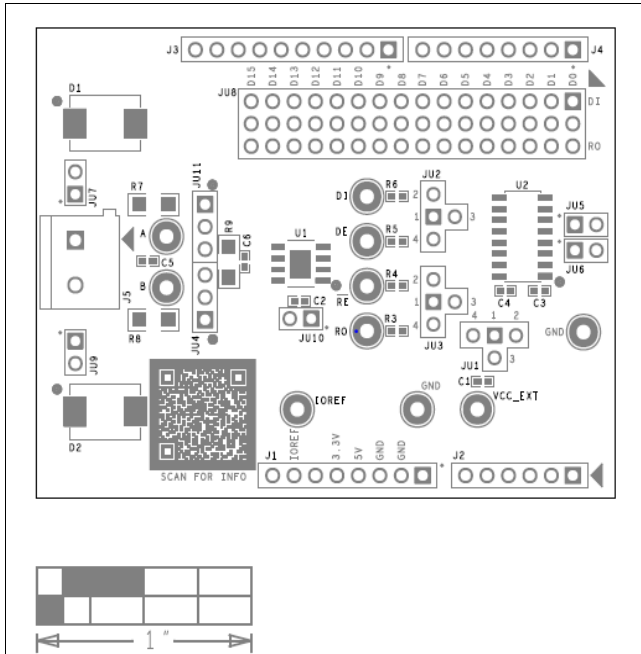
#Denotes RoHS-compliant.

MAX33074E Shield EV Kit Bill of Materials

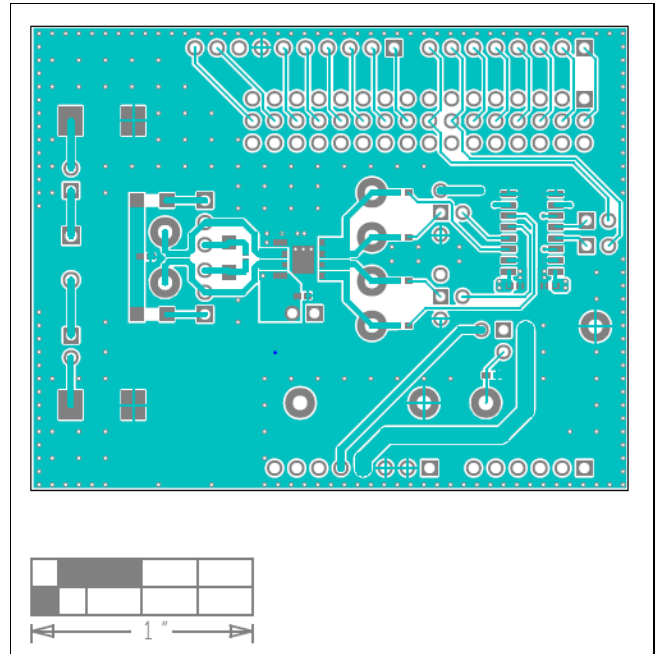
REF_DES	QTY	MFG PART#	VALUE	DESCRIPTION
A, B	2	5127	N/A	TEST POINT; PIN DIA=0.125IN; TOTAL LENGTH=0.445IN; BOARD HOLE=0.063IN; BLUE; PHOSPHOR BRONZE WIRE SILVER PLATE FINISH
C1	1	GRM155R60J106ME44; GRM155R60J106ME47; C1005X5R0J106M050BC; CL05A106MQ5NUN; C0402C106M9PAC	10UF	CAPACITOR; SMT (0402); CERAMIC CHIP; 10UF; 6.3V; TOL=20%; TG=-55 DEGC TO +85 DEGC; TC=X5R
C2-C4	3	C0402C104J4RAC; GCM155R71C104JA55	0.1UF	CAPACITOR; SMT (0402); CERAMIC CHIP; 0.1UF; 16V; TOL=5%; TG=-55 DEGC TO +125DEGC; TC=X7R
C5	1	C1005X7R1E473K050BC; GRM155R71E473K; GCM155R71E473KA55	0.047UF	CAPACITOR; SMT; 0402; CERAMIC CHIP; 0.047UF; 25V; TOL=10%; TG= -55 DEGC TO +125DEGC
C6	1	0402N500J500C	50PF	CAPACITOR; SMT (0402); CERAMIC; 50PF; 50V; 5%; C0G; -55DEGC TO +125DEGC;
DE, DI, RE, RO	4	5012	N/A	TEST POINT; PIN DIA=0.125IN; TOTAL LENGTH=0.445IN; BOARD HOLE=0.063IN; WHITE; PHOSPHOR BRONZE WIRE SILVER PLATE FINISH;
IREF	1	5125	N/A	TEST POINT; PIN DIA=0.125IN; TOTAL LENGTH=0.445IN; BOARD HOLE=0.063IN; BROWN; PHOSPHOR BRONZE WIRE SILVER PLATE FINISH;
J1, J4	2	SSQ-108-24-G-S	SSQ-108-24-G-S	CONNECTOR; FEMALE; THROUGH HOLE; 0.025INCH; SQ POST SOCKET; STRAIGHT; 8 PINS
J2	1	SSQ-106-24-G-S	SSQ-106-24-G-S	CONNECTOR; FEMALE; THROUGH HOLE; 0.025INCH; SQ POST SOCKET; STRAIGHT; 6 PINS
J3	1	SSQ-110-24-G-S	SSQ-110-24-G-S	CONNECTOR; FEMALE; THROUGH HOLE; 0.025INCH; SQ POST SOCKET; STRAIGHT; 10 PINS
J5	1	OSTTA024163	OSTTA024163	CONNECTOR; FEMALE; THROUGH HOLE; 5.08MM TERM BLOCK CONNECTOR; STRAIGHT; 2 PINS; -30 DEGC TO +105 DEGC
JU1-JU3	3	PEC04SAAN	PEC04SAAN	CONNECTOR; MALE; THROUGH HOLE; BREAKAWAY; STRAIGHT; 4 PINS
JU4, JU11	2	PEC03SAAN	PEC03SAAN	CONNECTOR, MALE; THROUGH HOLE; BREAKAWAY; STRAIGHT; 3 PINS
JU5-JU7, JU9, JU10	5	PCC02SAAN	PCC02SAAN	CONNECTOR, MALE; THROUGH HOLE; BREAKAWAY; STRAIGHT; 3 PINS; -65 DEGC TO +125 DEGC

JU8	1	TSW-116-07-T-T	TSW-116-07-T-T	CONNECTOR; MALE; THROUGH HOLE; 0.025IN SQ POST HEADER; STRAIGHT; 48PINS
R3-R6	4	ERJ-2GE0R00	0	RESISTOR; 0402; 0 OHM; 0%; JUMPER; 0.10W; THICK FILM
R7-R9	3	CRCW120660R0KNEAIF	60	RESISTOR; 1206; 60 OHM; 10%; 200PPM; 0.25W; THICJ FILM
SU1-SU3, SU5, SU6, SU8-SU10	8	S1100-B; SX1100-B; STC02SYAN	SX1100-B	TEST POINT; JUMPER; STR; TOATL LENGTH=0.24IN; BLACK; INSULATION=PBT; PHOSPHOR BRONZE CONTACT=GOLD PLATED
TP18, TP19	2	5011	N/A	TEST POINT; PIN DIA=0.125IN; TOTAL LENGTH=0.445IN; BOARD HOLE=0.063IN; BLACK; PHOSPHOR BRONZE WIRE SILVER PLATE FINISH
U1	1	MAX33074EASA+	MAX33074EASA+	EVKIT PART-IC; MAX33074E; CI25 -70V FAULT PROTECTED HALF DUPLEX RS-485; TRANSCEIVER; PACKAGE OUTLINE DRAWING: 21-0111; LAND PATTERN NUMBER: 90-0151; PACKAGE CODE: S8E+14C; NSOIC8-EP
U2	1	MAX14931FASE+	MAX14931FASE+	IC; DISO; 3/1 CHANNEL; 150MBPS; DEFAULT LOW; 2.75KVRMS DIGITAL ISOLATOR; NSOIC16 150MIL
VCC_EXT	1	5010	N/A	TEST POINT; PIN DIA=0.125IN; TOTAL LENGTH=0.445IN; BOARD HOLE=0.063IN; RED; PHOSPHOR BRONZE WIRE SIL;
PCB	1	MAX33074E	PCB	PCB:MAX33074E
D1, D2	0	SM15T30CA	25.6V	DIODE; TVS; SMC (DO-214AB); VRM=25.6V; IPP=36A

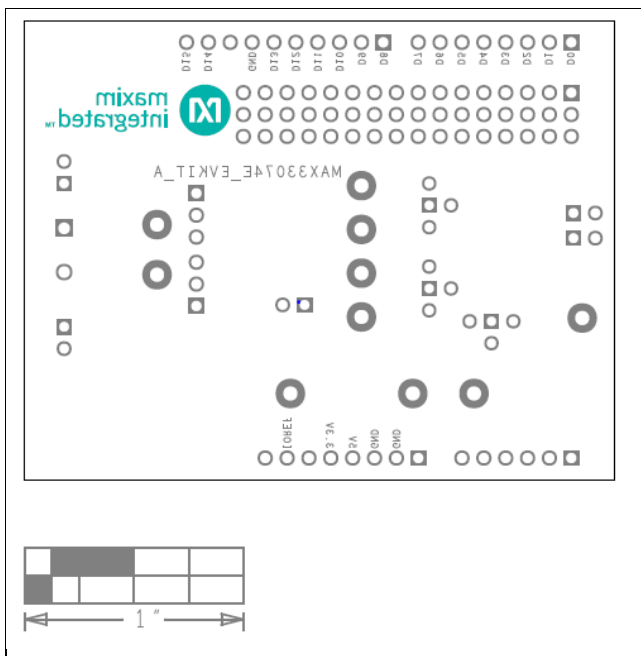
MAX33074E Shield PCB Layout



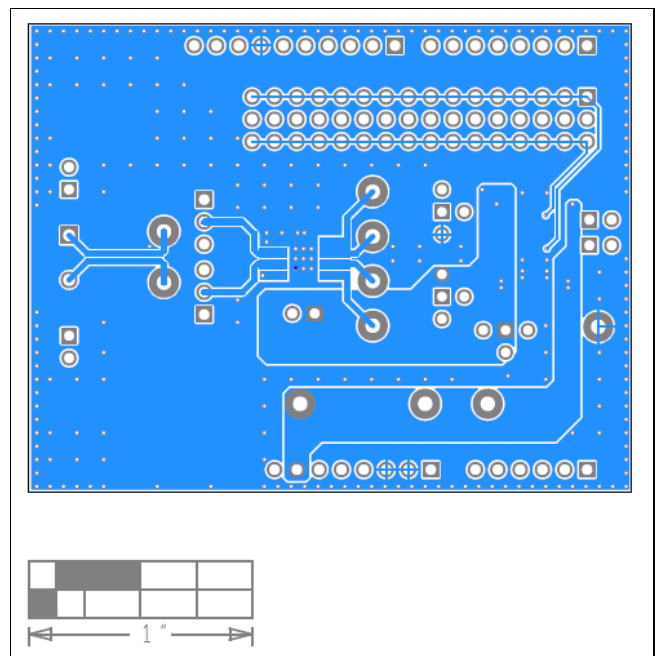
MAX33074E Shield PCB Layout—Top Silkscreen



MAX33074E Shield PCB Layout—Top Layer



MAX33074E Shield PCB Layout—Bottom Layer



MAX33074E Shield PCB Layout—Bottom Silkscreen

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	8/22	Initial release	—

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